



Material Content Data Sheet



Halogen-Free

Sales Product Name	BTS3125EJ	Issued	11. August 2021
MA#	MA005446228		
Package	PG-TDSO-8-31	Weight*	67.20 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.851	1.27	1.27	12665	12665
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		141	
	non noble metal	zinc	7440-66-6	0.038	0.06		565	
	non noble metal	iron	7439-89-6	0.760	1.13		11306	
	non noble metal	copper	7440-50-8	30.851	45.90	47.10	459068	471080
wire	non noble metal	copper	7440-50-8	0.203	0.30	0.30	3023	3023
encapsulation	organic material	carbon black	1333-86-4	0.098	0.15		1462	
	plastics	epoxy resin	-	3.832	5.70		57015	
	inorganic material	silicondioxide	60676-86-0	28.819	42.88	48.73	428829	487306
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7399	7399
plating	noble metal	silver	7440-22-4	0.825	1.23	1.23	12273	12273
glue	plastics	epoxy resin	-	0.074	0.11		1094	
	noble metal	silver	7440-22-4	0.347	0.52	0.63	5160	6254
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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